

74ALVCH16374

2.5 V/3.3 V 16-bit edge-triggered D-type flip-flop; 3-state

Rev. 5 — 9 July 2012

Product data sheet

1. General description

The 74ALVCH16374 is 16-bit edge-triggered flip-flop featuring separate D-type inputs for each flip-flop and 3-state outputs for bus oriented applications.

Incorporates bus hold data inputs which eliminate the need for external pull-up or pull-down resistors to hold unused inputs.

The 74ALVCH16374 consists of 2 sections of eight edge-triggered flip-flops. A clock (CP) input and an output enable ($\overline{OE}$) are provided per 8-bit section.

The flip-flops will store the state of their individual D-inputs that meet the set-up and hold time requirements on the LOW-to-HIGH CP transition.

When $\overline{OE}$ is LOW, the contents of the flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go the high-impedance OFF-state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Complies with JEDEC standard JESD8-B
- CMOS low power consumption
- MULTIBYTE flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Direct interface with TTL levels
- All data inputs have bus hold
- Output drive capability 50 Ω transmission lines at 85 °C
- Current drive ± 24 mA at $V_{CC} = 3.0$ V



3. Ordering information

Table 1. Ordering information

Type number	Temperature range	Package		
		Name	Description	Version
74ALVCH16374DL	−40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1
74LVCH16374DGG	−40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1

4. Functional diagram

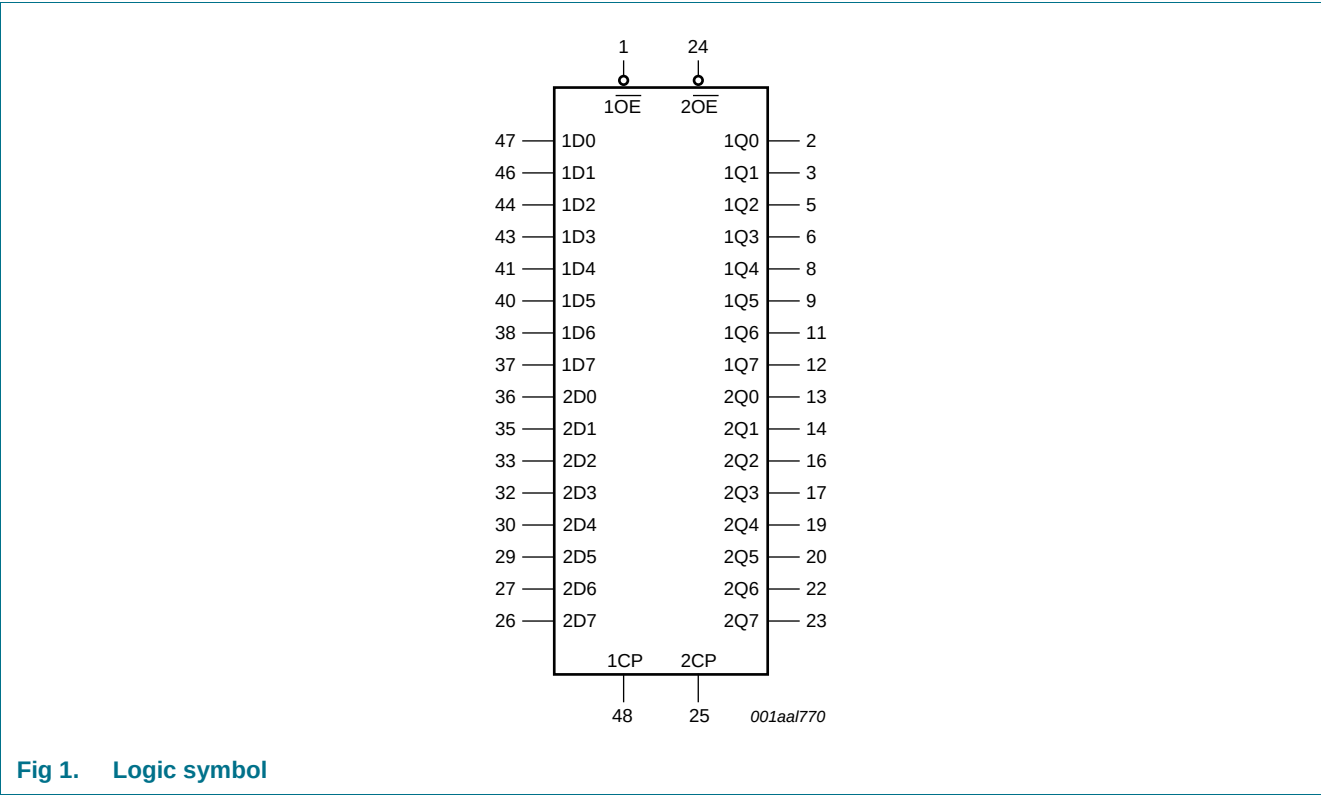


Fig 1. Logic symbol

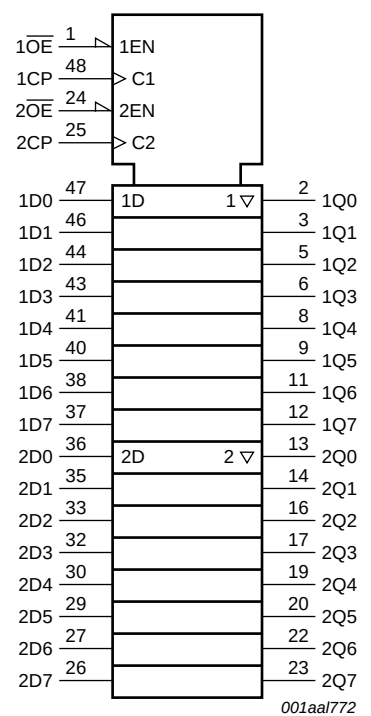


Fig 2. IEC logic symbol

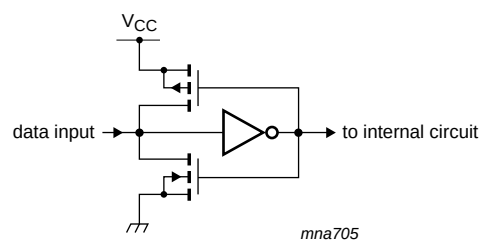


Fig 3. Bus hold circuit

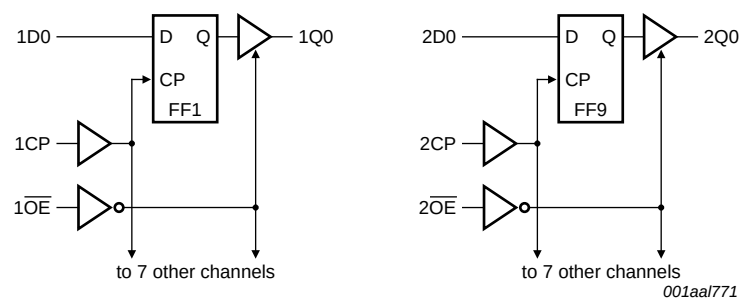


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning

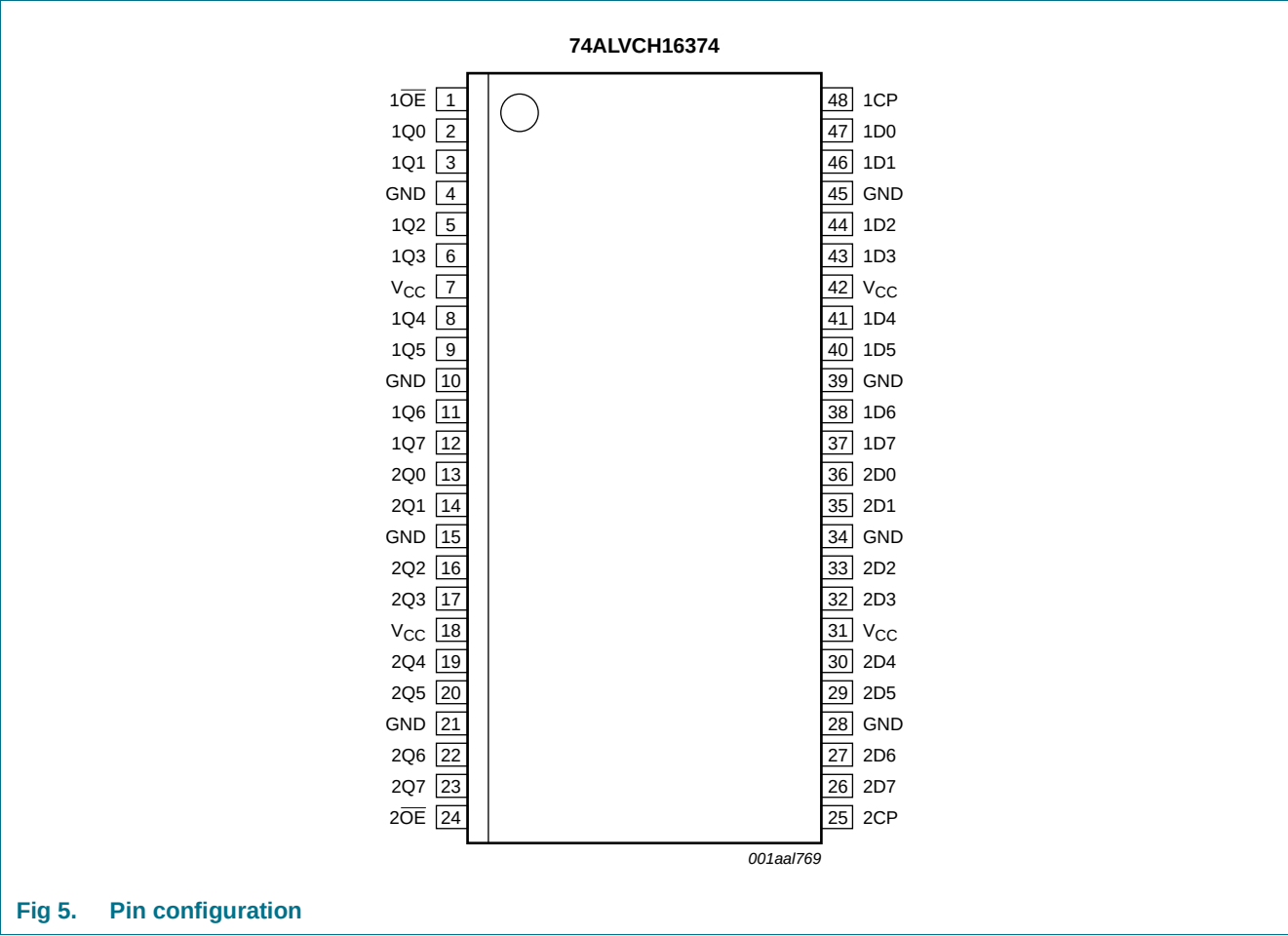


Fig 5. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{1OE}$, $\overline{2OE}$	1, 24	output enable input (active LOW)
1Q0 to 1Q7	2, 3, 5, 6, 8, 9, 11, 12	3-state flip-flop outputs
2Q0 to 2Q7	13, 14, 16, 17, 19, 20, 22, 23	3-state flip-flop outputs
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
V _{CC}	7, 18, 31, 42	positive supply voltage
1D0 to 1D7	47, 46, 44, 43, 41, 40, 38, 37	data inputs
2D0 to 2D7	36, 35, 33, 32, 30, 29, 27, 26	data inputs
1CP, 2CP	48, 25	clock input

6. Functional description

6.1 Function table

Table 3. Function table^[1]

Inputs			Internal flip-flops	Outputs Q0 to Q7	Operating mode
$\overline{nOE}$	nCP	Dn			
L	↑	l	L	L	load and read register
L	↑	h	H	H	
H	↑	l	L	Z	load register and disable outputs
H	↑	h	H	Z	

[1] H = HIGH voltage level;

L = LOW voltage level;

h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;

l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;

↑ = LOW-to-HIGH clock transition;

Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage	control inputs	[1] -0.5	+4.6	V
		data inputs	[1] -0.5	$V_{CC} + 0.5$	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
V_O	output voltage		[1] -0.5	$V_{CC} + 0.5$	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C;			
		SSOP48 package	[2] -	850	mW
		TSSOP48 package	[3] -	600	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] Above 55 °C the value of P_{tot} derates linearly with 11.3 mW/K.

[3] Above 55 °C the value of P_{tot} derates linearly with 8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage	maximum speed performance				
		$C_L = 30$ pF	2.3	-	2.7	V
		$C_L = 50$ pF	3.0	-	3.6	V
		low voltage applications	1.2	-	3.6	V
V_I	input voltage	data inputs	0	-	V_{CC}	V
		control inputs	0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.3$ V to 3.0 V	0	-	20	ns/V
		$V_{CC} = 3.0$ V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
T_{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	V _{CC}	-	-	V
		V _{CC} = 1.8 V	0.7V _{CC}	0.9	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	1.2	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	1.5	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0	V
		V _{CC} = 1.8 V	-	0.9	0.2V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	1.2	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	1.5	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -100 µA; V _{CC} = 1.8 V to 3.6 V	V _{CC} - 0.2	V _{CC}	-	V
		I _O = -6 mA; V _{CC} = 1.8 V	V _{CC} - 0.4	V _{CC} - 0.1	-	V
		I _O = -6 mA; V _{CC} = 2.3 V	V _{CC} - 0.3	V _{CC} - 0.08	-	V
		I _O = -12 mA; V _{CC} = 2.3 V	V _{CC} - 0.5	V _{CC} - 0.17	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	V _{CC} - 0.5	V _{CC} - 0.14	-	V
		I _O = -18 mA; V _{CC} = 2.3 V	V _{CC} - 0.6	V _{CC} - 0.26	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	V _{CC} - 1.0	V _{CC} - 0.28	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 100 µA; V _{CC} = 1.8 V to 3.6 V	-	0	0.20	V
		I _O = 6 mA; V _{CC} = 1.8 V	-	0.09	0.30	V
		I _O = 6 mA; V _{CC} = 2.3 V	-	0.07	0.20	V
		I _O = 12 mA; V _{CC} = 2.3 V	-	0.15	0.40	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	0.14	0.40	V
		I _O = 18 mA; V _{CC} = 2.3 V	-	0.23	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	0.27	0.55	V
I _I	input leakage current	V _{CC} = 1.8 V to 3.6 V				
		control input; V _I = 5.5 V or GND	-	0.1	5	µA
		data input; V _I = V _{CC} or GND	-	0.1	5	µA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND				
		V _{CC} = 1.8 V to 2.7 V	-	0.1	5	µA
		V _{CC} = 2.7 V to 3.6 V	-	0.1	10	µA
I _{LIZ}	OFF-state input leakage current	V _I = V _{CC} or GND				
		V _{CC} = 1.8 V to 2.7 V	-	0.1	10	µA
		V _{CC} = 3.6 V	-	0.1	15	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A;				
		V _{CC} = 1.8 V to 2.7 V	-	0.1	20	µA
		V _{CC} = 2.7 V to 3.6 V	-	0.2	40	µA

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6\text{ V}$; $I_O = 0\text{ A}$; $V_{CC} = 2.7\text{ V}$ to 3.6 V				
		per control input	-	5	500	μA
		per data I/O input	-	150	750	μA
I_{BHL}	bus hold LOW current	$V_{CC} = 2.3\text{ V}$; $V_I = 0.7\text{ V}$	[2]	45	-	μA
		$V_{CC} = 3.0\text{ V}$; $V_I = 0.8\text{ V}$	[2]	75	150	μA
I_{BHH}	bus hold HIGH current	$V_{CC} = 2.3\text{ V}$; $V_I = 1.7\text{ V}$	[2]	-45	-	μA
		$V_{CC} = 3.0\text{ V}$; $V_I = 2.0\text{ V}$	[2]	-75	-175	μA
I_{BHLO}	bus hold LOW overdrive current	$V_{CC} = 2.7\text{ V}$	[2]	300	-	μA
		$V_{CC} = 3.6\text{ V}$	[2]	450	-	μA
I_{BHHO}	bus hold HIGH overdrive current	$V_{CC} = 2.7\text{ V}$	[2]	-300	-	μA
		$V_{CC} = 3.6\text{ V}$	[2]	-450	-	μA
C_I	input capacitance		-	5.0	-	pF

[1] All typical values are measured at $T_{amb} = 25\text{ }^\circ\text{C}$.

[2] Valid for data inputs of bus hold parts only.

10. Dynamic characteristics

Table 7. Dynamic characteristicsAt recommended operating conditions. Voltages are referenced to GND (ground = 0 V); test circuit [Figure 9](#).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$						
f_{max}	maximum frequency	see Figure 6				
		$V_{CC} = 1.8\text{ V}$	125	250	-	MHz
		$V_{CC} = 2.3\text{ V}$ to 2.7 V	[2]	150	300	MHz
		$V_{CC} = 2.7\text{ V}$	150	300	-	MHz
		$V_{CC} = 3.0\text{ V}$ to 3.6 V	[3]	200	350	MHz
t_{pd}	propagation delay	nCP to nQn; see Figure 6	[4]			
		$V_{CC} = 1.2\text{ V}$	-	7.7	-	ns
		$V_{CC} = 1.8\text{ V}$	1.5	3.6	6.5	ns
		$V_{CC} = 2.3\text{ V}$ to 2.7 V	[2]	1.0	2.3	ns
		$V_{CC} = 2.7\text{ V}$	1.0	2.3	3.8	ns
		$V_{CC} = 3.0\text{ V}$ to 3.6 V	[3]	1.0	2.4	ns
t_{en}	enable time	nOE to nQn; see Figure 7	[4]			
		$V_{CC} = 1.2\text{ V}$	-	8.7	-	ns
		$V_{CC} = 1.8\text{ V}$	1.5	4.0	7.2	ns
		$V_{CC} = 2.3\text{ V}$ to 2.7 V	[2]	1.0	2.6	ns
		$V_{CC} = 2.7\text{ V}$	1.0	2.9	4.8	ns
		$V_{CC} = 3.0\text{ V}$ to 3.6 V	[3]	1.0	2.3	ns

Table 7. Dynamic characteristics ...continuedAt recommended operating conditions. Voltages are referenced to GND (ground = 0 V); test circuit [Figure 9](#).

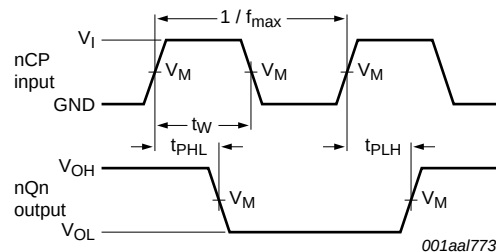
Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
t _{dis}	disable time	nOE to nQn; see Figure 7				
		V _{CC} = 1.2 V	-	6.2	-	ns
		V _{CC} = 1.8 V	1.5	3.1	5.4	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.1	4.0	ns
		V _{CC} = 2.7 V	1.0	2.9	4.5	ns
t _w	pulse width	V _{CC} = 3.0 V to 3.6 V	1.0	2.6	4.1	ns
		nCP HIGH or LOW; see Figure 6				
		V _{CC} = 1.8 V	4.0	2.0	-	ns
		V _{CC} = 2.3 V to 2.7 V	3.0	1.6	-	ns
		V _{CC} = 2.7 V	3.0	1.6	-	ns
t _{su}	set-up time	V _{CC} = 3.0 V to 3.6 V	2.5	1.4	-	ns
		Dn to nCP; see Figure 8				
		V _{CC} = 1.8 V	1.5	0.2	-	ns
		V _{CC} = 2.3 V to 2.7 V	1.2	0.2	-	ns
		V _{CC} = 2.7 V	1.5	0.4	-	ns
t _h	hold time	V _{CC} = 3.0 V to 3.6 V	1.2	0.2	-	ns
		Dn to nCP; see Figure 8				
		V _{CC} = 1.8 V	0.6	-0.2	-	ns
		V _{CC} = 2.3 V to 2.7 V	0.8	-0.1	-	ns
		V _{CC} = 2.7 V	0.6	-0.2	-	ns
C _{PD}	power dissipation capacitance	V _{CC} = 3.0 V to 3.6 V	0.8	0.0	-	ns
		per flip-flop; V _I = GND to V _{CC}				
		outputs enabled	-	16	-	pF
		outputs disabled	-	10	-	pF

[1] All typical values are measured at T_{amb} = 25 °C.[2] Typical values are measured at V_{CC} = 2.5 V.[3] Typical values are measured at V_{CC} = 3.3 V.[4] t_{pd} is the same as t_{PLH} and t_{PHL}.t_{en} is the same as t_{PZL} and t_{PZH}.t_{dis} is the same as t_{PLZ} and t_{PHZ}.[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).P_D = C_{PD} × V_{CC}² × f_i × N + Σ(C_L × V_{CC}² × f_o) where:f_i = input frequency in MHz; f_o = output frequency in MHz;C_L = output load capacitance in pF;V_{CC} = supply voltage in Volts;

N = number of inputs switching;

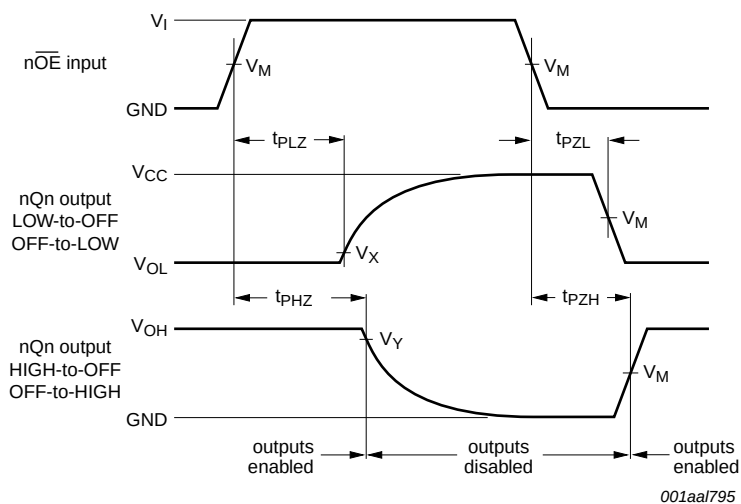
Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

11. Waveforms



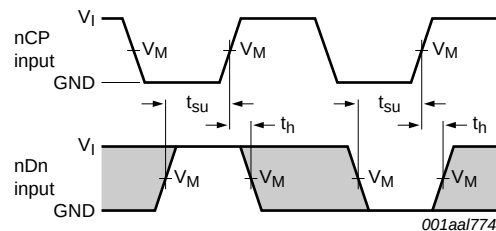
Measurement points are given in [Table 8](#).
VOL and VOH are typical output levels that occur with the output load.

Fig 6. Propagation delay, clock input (nCP) to data output (nQn), and pulse width



Measurement points are given in [Table 8](#).
VOL and VOH are typical output levels that occur with the output load.

Fig 7. 3-state enable and disable times



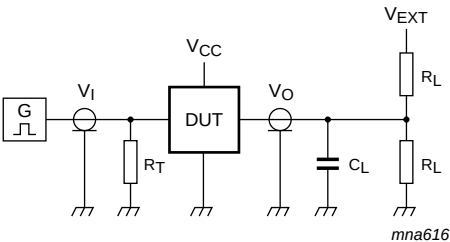
The shaded areas indicate when the input is permitted to change for predictable output performance.

Fig 8. Data setup and hold times for input (nDn) to input (nCP)

Table 8. Measurement points

Supply voltage	Input		Output		
V _{CC}	V _I	V _M	V _M	V _X	V _Y
2.3 V to 2.7 V and < 2.3 V	V _{CC}	0.5 × V _{CC}	0.5 × V _{CC}	V _{OL} + 0.15 V	V _{OH} − 0.15 V
2.7 V	2.7 V	1.5 V	1.5 V	V _{OL} + 0.3 V	V _{OH} − 0.3 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V	V _{OL} + 0.3 V	V _{OH} − 0.3 V

12. Test information



Test data is given in [Table 9](#).
Definitions for test circuit:
RL = Load resistance.
CL = Load capacitance including jig and probe capacitance.
RT = Termination resistance should be equal to output impedance Z₀ of the pulse generator.
V_{EXT} = External voltage for measuring switching times.

Fig 9. Load circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V _{EXT}		
V _{CC}	V _I	t _r , t _f	C _L	R _L	t _{PLH} , t _{PHL}	t _{PLZ} , t _{PZL}	t _{PHZ} , t _{PZH}
2.3 V to 2.7 V and < 2.3 V	V _{CC}	≤ 2.0 ns	30 pF	500 Ω	open	2 × V _{CC}	GND
2.7 V	2.7 V	2.5 ns	50 pF	500 Ω	open	2 × V _{CC}	GND
3.0 V to 3.6 V	2.7 V	2.5 ns	50 pF	500 Ω	open	2 × V _{CC}	GND

13. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm SOT370-1

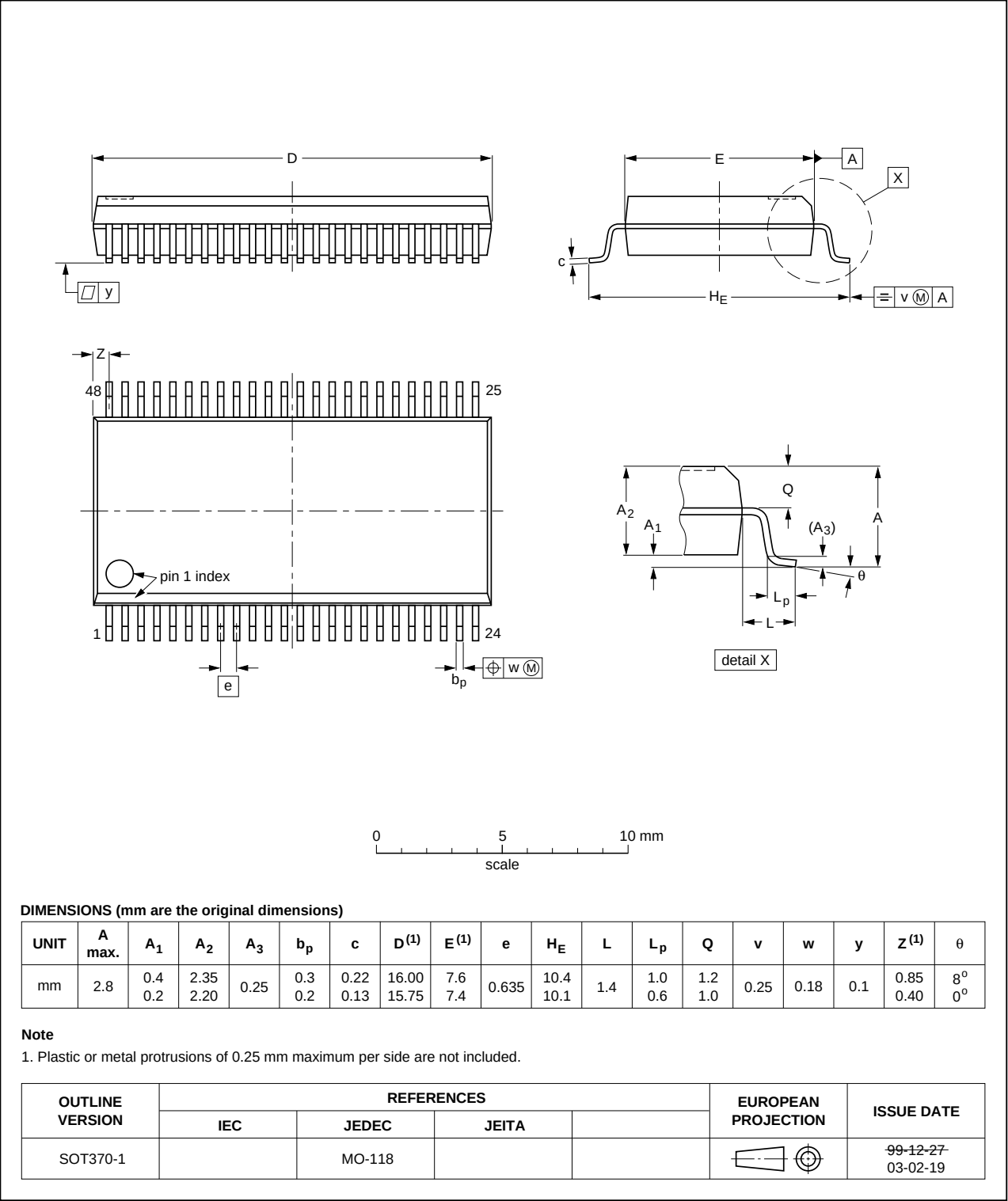


Fig 10. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1

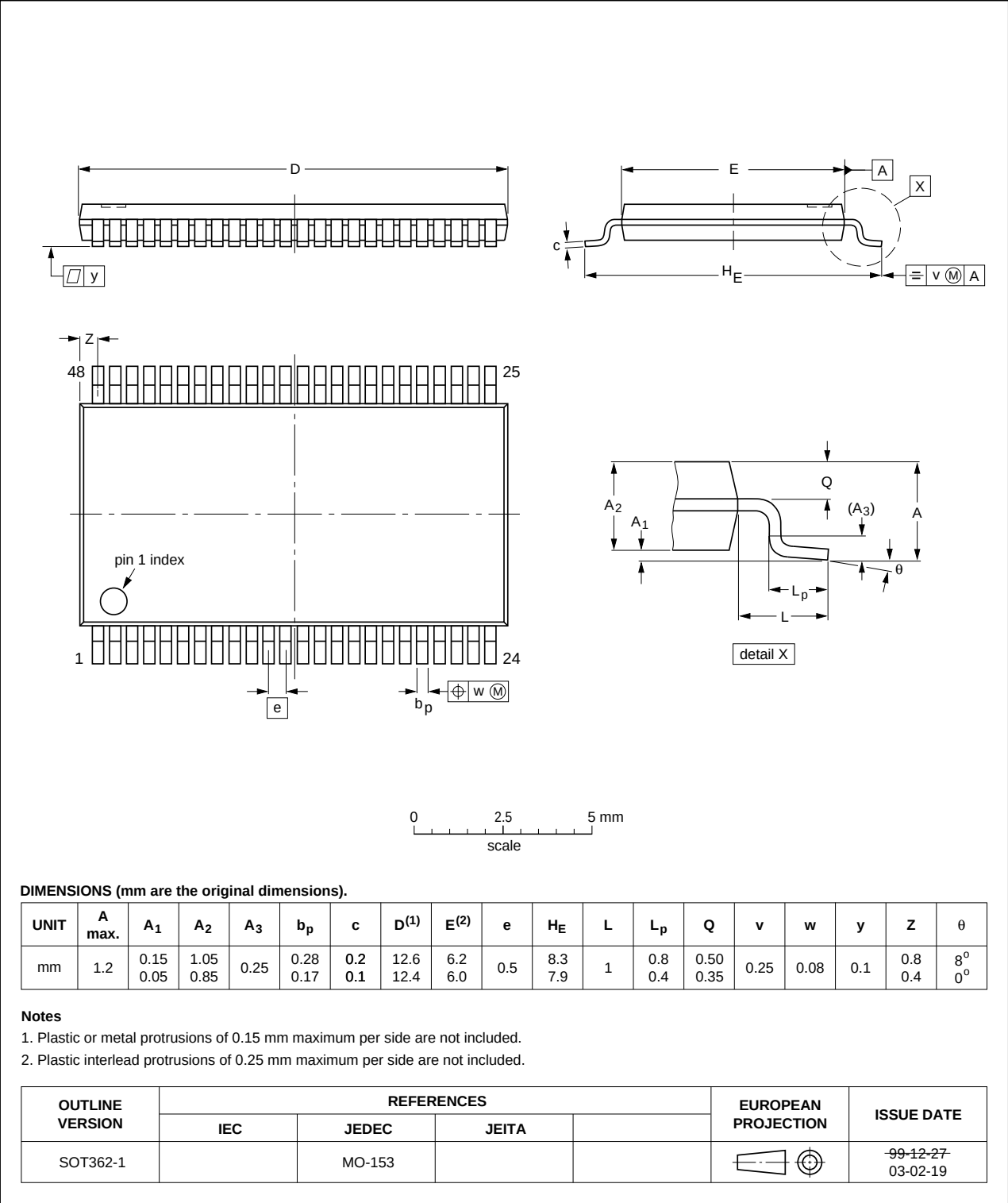


Fig 11. Package outline SOT362-1 (TSSOP48)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVCH16374 v.5	20120709	Product data sheet	-	74ALVCH16374 v.4
Modifications:	• Table 8 corrected (errata).			
74ALVCH16374 v.4	20111117	Product data sheet	-	74ALVCH16374 v.3
Modifications:	• Legal pages updated.			
74ALVCH16374 v.3	20100427	Product data sheet	-	74ALVCH16374 v.2
74ALVCH16374 v.2	19980618	Product specification	-	74ALVCH16374 v.1

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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